

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 05-129357

(43)Date of publication of application : 25.05.1993

(51)Int.CI.

H01L 21/60

(21)Application number : 03-287992 (71)Applicant : TANAKA DENSHI KOGYO KK

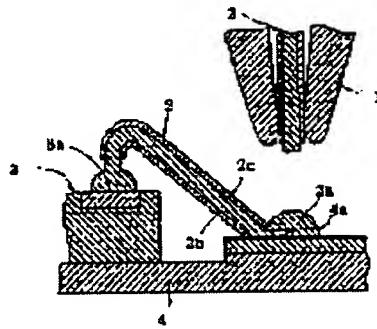
(22)Date of filing : 01.11.1991 (72)Inventor : KAWAGUCHI HIDEAKI
HANADA SHINICHI

(54) BONDING WIRE

(57)Abstract:

PURPOSE: To enable a wire to be cut off at a specific position simply by lifting a capillary after performing the reinforcement ball bonding step by a method wherein the wire is made of high purity Au containing a specific amount of Y and one or two kinds of respectively specific amounts of Ge and Be.

CONSTITUTION: A wire 2 let out of a capillary 1 is ball-bonded on the first bonding position 3 and after stitch-bonding at the second bonding position 4a, the wire 2 successively let out of the capillary 1 is ball-bonded onto the stitch- bonded part to be cut off. At this time, the bonding wire 2 is made of high purity Au containing 100-1000wtppm and one or two kinds of 30-100wtppm of Ge and 5-15wtppm of Be. Otherwise, the wire 2 is made of high purity Au containing 100-500wtppm of Y and 5-100wtppm of Ca and so forth.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of
rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2000 Japanese Patent Office